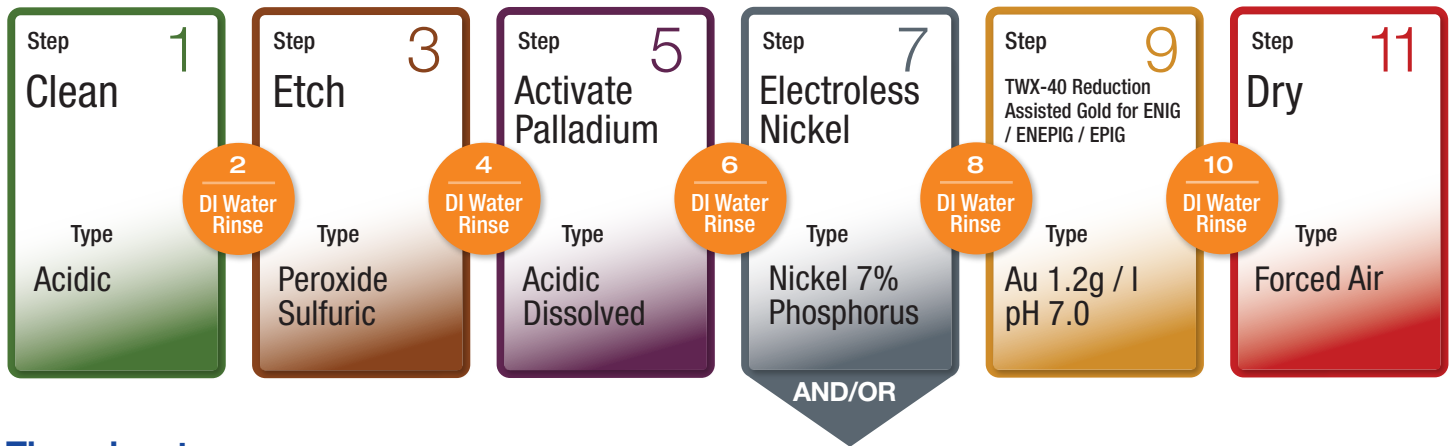


# Need Additional Final Finish Capability But Want to Avoid High Capital Costs?

Uyemura has a solution, with chemistry that seamlessly converts an existing ENIG or ENEPIG line into one that's fully capable of processing ENIG, ENEPIG and EPIG.

This is achievable with just a few chemical modifications, and virtually no downtime. There's also an important added benefit: the ability to deposit heavier gold – an increasingly common requirement - while meeting the IPC 4552 nickel corrosion requirement.



## The advantages:

- ▶ One line for all three final finishes that are critical to conventional as well as the newer high frequency applications.
- ▶ The ability to process the finer geometries required by higher signal speed.
- ▶ Heavier gold deposition that enhances wire bonding and harsh environment reliability.
- ▶ Enhanced compliance with IPC corrosion specifications.

Step  
Electroless Palladium  
Type  
Palladium 3% Phosphorus

This Uyemura in-line solution creates lucrative new opportunities for board shops and OEMs. Contact your Uyemura representative for details.

## UYEMURA INTERNATIONAL CORPORATION



North America's Leading Experts in Final Finishes, Via Fills, Acid and Electroless Coppers, Immersion Silver and Tin; also MEC Surface Treatments and Auruna Gold Electrolytes.

**Corporate Headquarters:** 3990 Concoors, #425 • Ontario, CA 91764 • ph: (909) 466-5635  
**Tech Center:** 240 Town Line Road • Southington, CT 06489 • ph: (860) 793-4011



[UYEMURA.COM](http://UYEMURA.COM)